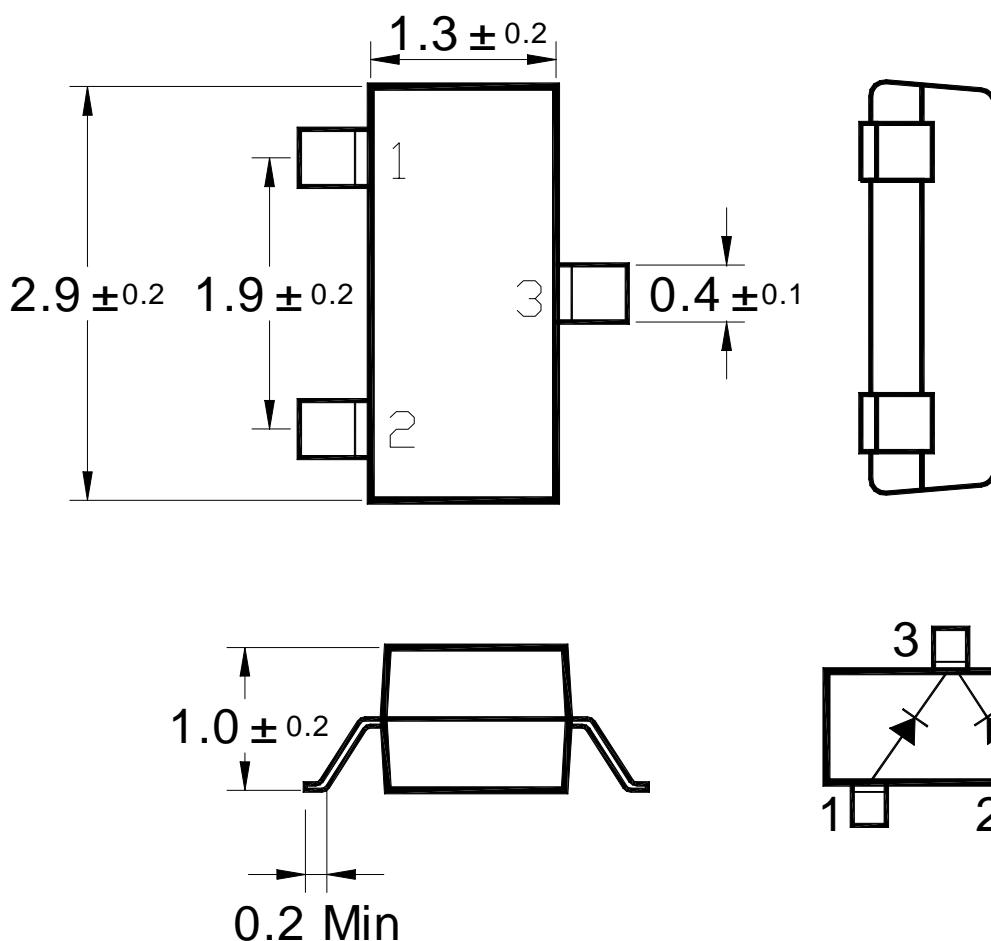


## Features

- Compact type
- Radiation size 1.3mm × 2.9mm
- Radiation color (Red, Green)
- Surface mount lead configuration

## Outline Dimensions

unit : mm



### PIN Connections

1. Anode
2. Anode
3. Cathode

**Absolute maximum ratings**

Characteristic	Symbol	Ratings	Unit
Power Dissipation	P <sub>D</sub>	55	mW
Forward Current	I <sub>F</sub>	30	mA
* <sup>1</sup> Peak Forward Current	I <sub>FP</sub>	50	mA
Reverse Voltage	V <sub>R</sub>	4	V
Operating Temperature	T <sub>opr</sub>	-25 85	
Storage Temperature	T <sub>stg</sub>	-30 100	
* <sup>2</sup> Soldering Temperature	T <sub>sol</sub>	240 for 5 seconds	

\*1.Duty ratio = 1/16, Pulse width = 0.1ms

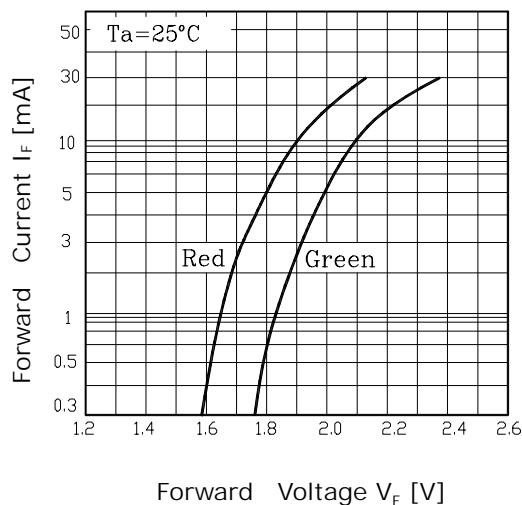
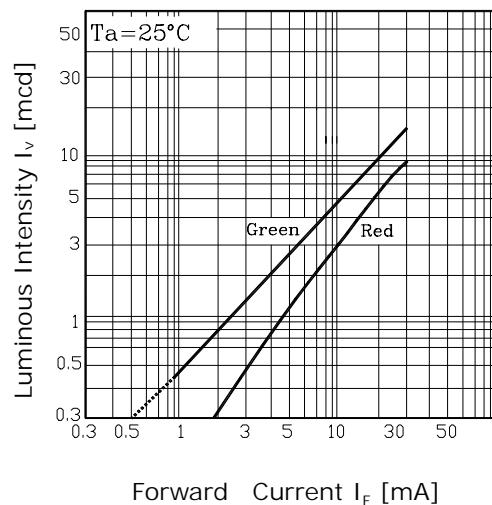
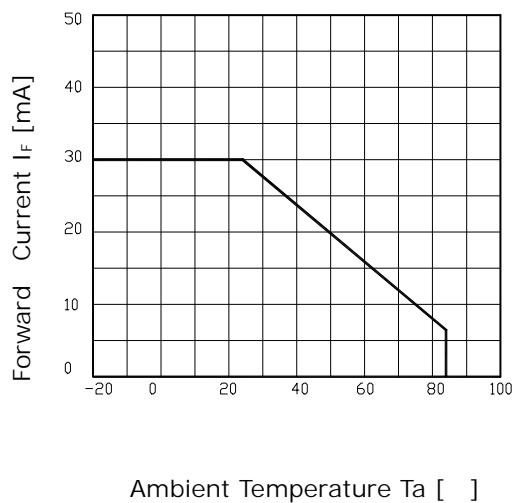
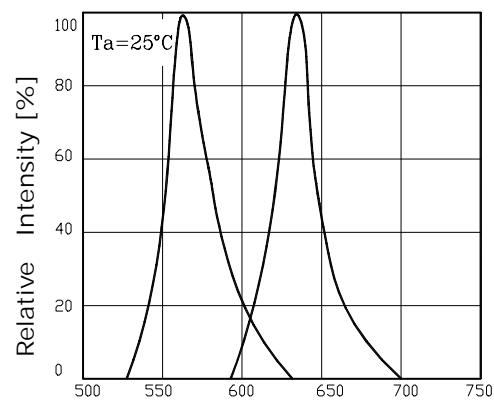
\*2.Recommended soldering condition ⇒ Attached

**Electrical Characteristics**

Characteristic	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20mA	-	2.0	2.7	V
			-	2.1	2.8	
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20mA	-	6	-	mcd
			-	10	-	
Peak Wavelength	λ <sub>P</sub>	I <sub>F</sub> = 20mA	-	630	-	nm
			-	570	-	
Spectrum Bandwidth		I <sub>F</sub> = 20mA	-	35	-	nm
			-	30	-	
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =4V	-	-	10	uA
* <sup>3</sup> Half angle	θ1/2	I <sub>F</sub> = 20mA	-	±80	-	deg

\*3. θ1/2 is the off-axis angle where the luminous intensity is 1/2 the peak intensity

## Characteristic Diagrams

**Fig. 1  $I_F - V_F$** **Fig. 2  $I_V - I_F$** **Fig. 3  $I_F - Ta$** **Fig. 4 Spectrum Distribution****Fig. 5 Radiation Diagram**